

Material Declaration Report



Package Type:	TQFN 36L
Pericom Package Code:	ZF36(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A
REACH Compliance:	Yes
Halogen Free:	Yes

Component Weight (mg):	72.573
Termination Plating:	NiPdAu
JESD 97 Pb-free Category:	e4
Plating Thickness (um):	0.5-2.2
Tin Whisker Mitigation:	N/A

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	3/26/2010

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)			
MOLD COMPOUND	41.420	UTL	Epoxy Resin	Trade secret	6.800	2.817			
			Phenol resin	Trade secret	3.000	1.243			
			Carbon black	1333-86-4	0.200	0.083			
			Silica fused	60676-86-0	90.000	37.278			
		SPEL	Silica	60676-86-0	90.150	37.340			
			Phenol resin	Proprietary	3.500	1.450			
			Epoxy Resin-1	Proprietary	1.750	0.725			
			Epoxy Resin-2	Proprietary	1.750	0.725			
			Epoxy Resin-3	Proprietary	1.750	0.725			
			Others Non-hazardous Material	Proprietary	1.000	0.414			
		GTK	Carbon Black	1333-86-4	0.100	0.041			
			Epoxy Resin	Trade secret	8.000	3.314			
			Phenol Resin	Trade secret	6.000	2.485			
			Silica fused	60676-86-0	75.000	31.065			
			Silica fused	7631-86-9	10.000	4.142			
LEADFRAME	26.631		Silica crystalline	14808-60-7	0.500	0.207			
			Carbon Black	1333-86-4	0.500	0.207			
			Copper	7440-50-8	96.953	25.820			
			Iron	7439-89-6	2.350	0.626			
			Zinc	7440-66-6	0.111	0.030			
			Phosphorus	7723-14-0	0.065	0.017			
SILICON DIE	2.590		Nickel	7440-02-0	0.473	0.126			
			Palladium	7440-05-3	0.041	0.011			
			Gold	7440-57-5	0.007	0.002			
			Silicon (Si)	7440-21-3	99.192	2.569			
			Non-hazardous Metal	Proprietary	0.808	0.021			
			DIE ATTACH EPOXY	1.253	UTL	Epoxy Resin	Proprietary	31.000	0.388
						Metal Oxide	Proprietary	31.000	0.388
Glycol Ethers	Proprietary	21.000				0.263			
Curing Agent & Hardener	Proprietary	8.500				0.107			
Treated Silica	14808-60-7	8.500				0.107			
SPEL	Silver	7440-22-4			80.000	1.002			
	Epoxy Resin	9003-36-5			10.000	0.125			
	Diluent	26447-14-3			6.000	0.075			
GTK	Hardener	620-92-8			3.500	0.044			
	Dicyandamide	461-58-5			0.500	0.006			
GOLD WIRE	0.679		Silver	7440-22-4	80.000	1.002			
			Acrylate Resin	Proprietary	16.000	0.200			
			Heterocyclic organic compound	Proprietary	2.000	0.025			
			Treated Silica	7631-86-9	2.000	0.025			
GOLD WIRE	0.679		Gold(Au)	7440-57-5	99.990	0.679			
			Impurities	-	0.010	0.000			

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
	<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm													
O	O	O	O	O	O													
O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.																		